

**IN THE
UNITED STATES PATENT & TRADEMARK OFFICE**

IN REMAINING APPLICATION
OF:

Toshihide ITO, et al.

) **EXPRESS MAIL**
) **CERTIFICATE OF**
) **MAILING FOR:**

CASE:

200335-0037

) RCE Application

SERIAL NO.:

09/671,084

FILED ON:

September 27, 2000

FOR:

Sn-Ag-Cu SOLDER AND SURFACE TREATMENT AND PARTS MOUNTING METHODS USING THE SAME

ASSISTANT COMMISSIONER OF PATENTS
WASHINGTON, DC 20231

Dear Sirs:

[X] AUTHORIZATION TO PAY AND PETITION FOR THE ACCEPTANCE OF ANY NECESSARY FEES: If any charges or fees must be paid in connection with the following Communication (including but not limited to the payment of issue fees), they may be paid out of our deposit account No. 50-1965. If this payment also requires a Petition, please construe this authorization to pay as the necessary Petition which is required to accompany the payment.

INFORMATION DISCLOSURE STATEMENT

Applicant submits herewith a list of prior art (PTO form 1449) which should be placed of record in the above identified application.

It is believed that the present invention clearly distinguishes over the enclosed prior art.

Dated:

By:

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EXPRESS MAIL mailing label No. EV054553373US

Date of Deposit: August 9, 2002

I hereby certify that the above listed papers or fees are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above, addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. The person mailing these papers/fees is:

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SIGNATURE _____

Sheila E. Brown

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